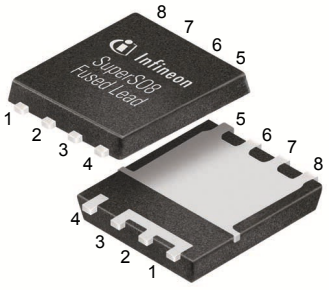
MOSFET

OptiMOS™ Power-MOSFET, 40 V

TDSON-8 FL (enlarged source interconnection)



Features

- Optimized for synchronous rectification
- Integrated monolithic Schottky-like diode
- Very low on-resistance $R_{DS(on)}$
- 100% avalanche tested
- N-channel, logic level
- Qualified according to JEDEC[1] for target applications
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21
- Higher solder joint reliability due to enlarged source interconnection

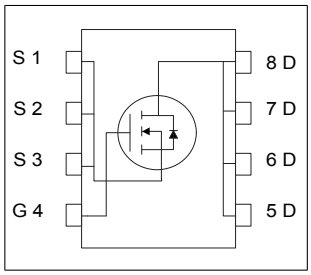


Table 1 Key Performance Parameters

Parameter	Value	Unit
V_{DS}	40	V
$R_{DS(on),max}$	1.45	mΩ
I_D	195	A
Q_{OSS}	53	nC
Q_G(0V..10V)	55	nC

Type / Ordering Code	Package	Marking	Related Links
BSC014N04LSI	TDSON-8 FL	014N04LI	-

[1] J-STD20 and JESD22

Table of Contents

Description 1
Maximum ratings 3
Thermal characteristics 3
Electrical characteristics 4
Electrical characteristics diagrams 6
Package Outlines 10
Revision History 13
Trademarks 13
Disclaimer 13

1 Maximum ratings

at T_A=25 °C, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current[1]	I_D	- - - - -	- - - - -	195 123 166 105 31	A	V_{GS}=10 V, T_C=25 °C V_{GS}=10 V, T_C=100 °C V_{GS}=4.5 V, T_C=25 °C V_{GS}=4.5 V, T_C=100 °C V_{GS}=10 V, T_A=25 °C, R_{thJA}=50 K/W[2]
Pulsed drain current[3]	$I_{D,pulse}$	-	-	780	A	T_C=25 °C
Avalanche current, single pulse[4]	I_{AS}	-	-	50	A	T_C=25 °C
Avalanche energy, single pulse	E_{AS}	-	-	90	mJ	I_D=50 A, R_{GS}=25 Ω
Gate source voltage	V_{GS}	-20	-	20	V	-
Power dissipation	P_{tot}	- -	- -	96 2.5	W	T_C=25 °C T_A=25 °C, R_{thJA}=50 K/W[2]
Operating and storage temperature	T_j, T_{stg}	-55	-	150	°C	IEC climatic category; DIN IEC 68-1: 55/150/56

2 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case, bottom	R_{thJC}	-	0.8	1.3	K/W	-
Thermal resistance, junction - case, top	R_{thJC}	-	-	20	K/W	-
Device on PCB, 6 cm² cooling area[2]	R_{thJA}	-	-	50	K/W	-

[1] Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature at 25°C. For higher case temperature please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.
[2] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.
[3] See Diagram 3 for more detailed information
[4] See Diagram 13 for more detailed information

3 Electrical characteristics

at T_j=25 °C, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	40	-	-	V	V_{GS}=0 V, I_D=10 mA
Breakdown voltage temperature coefficient	$dV_{(BR)DSS}/dT_j$	-	30	-	mV/K	I_D=10 mA, referenced to 25 °C
Gate threshold voltage	$V_{GS(th)}$	1.2	-	2	V	V_{DS}=V_{GS}, I_D=250 µA
Zero gate voltage drain current	I_{DSS}	- -	- 2	0.5 -	mA	V_{DS}=32 V, V_{GS}=0 V, T_j=25 °C V_{DS}=32 V, V_{GS}=0 V, T_j=125 °C
Gate-source leakage current	I_{GSS}	-	10	100	nA	V_{GS}=20 V, V_{DS}=0 V
Drain-source on-state resistance	$R_{DS(on)}$	- -	1.5 1.2	2 1.45	mΩ	V_{GS}=4.5 V, I_D=50 A V_{GS}=10 V, I_D=50 A
Gate resistance[1)]	R_G	0.45	0.9	1.8	Ω	-
Transconductance	g_{fs}	110	220	-	S	$\|V_{DS}\|>2\|I_D\|R_{DS(on)max}$, I_D=50 A

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance[1)]	C_{iss}	-	4000	5600	pF	V_{GS}=0 V, V_{DS}=20 V, f=1 MHz
Output capacitance[1)]	C_{oss}	-	1200	1680	pF	V_{GS}=0 V, V_{DS}=20 V, f=1 MHz
Reverse transfer capacitance[1)]	C_{rss}	-	90	180	pF	V_{GS}=0 V, V_{DS}=20 V, f=1 MHz
Turn-on delay time	$t_{d(on)}$	-	16	-	ns	V_{DD}=20 V, V_{GS}=10 V, I_D=30 A, $R_{G,ext}$,ext=1.6 Ω
Rise time	t_r	-	50	-	ns	V_{DD}=20 V, V_{GS}=10 V, I_D=30 A, $R_{G,ext}$,ext=1.6 Ω
Turn-off delay time	$t_{d(off)}$	-	55	-	ns	V_{DD}=20 V, V_{GS}=10 V, I_D=30 A, $R_{G,ext}$,ext=1.6 Ω
Fall time	t_f	-	11	-	ns	V_{DD}=20 V, V_{GS}=10 V, I_D=30 A, $R_{G,ext}$,ext=1.6 Ω

[1)] Defined by design. Not subject to production test

Table 6 Gate charge characteristics[1)]

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	9.9	-	nC	V_{DD}=20 V, I_D=50 A, V_{GS}=0 to 10 V
Gate charge at threshold	$Q_{g(th)}$	-	6.3	-	nC	V_{DD}=20 V, I_D=50 A, V_{GS}=0 to 10 V
Gate to drain charge[2)]	Q_{gd}	-	8.9	12.5	nC	V_{DD}=20 V, I_D=50 A, V_{GS}=0 to 10 V
Switching charge	Q_{sw}	-	12	-	nC	V_{DD}=20 V, I_D=50 A, V_{GS}=0 to 10 V
Gate charge total[2)]	Q_g	-	55	77	nC	V_{DD}=20 V, I_D=50 A, V_{GS}=0 to 10 V
Gate plateau voltage	$V_{plateau}$	-	2.5	-	V	V_{DD}=20 V, I_D=50 A, V_{GS}=0 to 10 V
Gate charge total[2)]	Q_g	-	29	41	nC	V_{DD}=20 V, I_D=50 A, V_{GS}=0 to 4.5 V
Gate charge total, sync. FET	$Q_{g(sync)}$	-	49	-	nC	V_{DS}=0.1 V, V_{GS}=0 to 10 V
Output charge[2)]	Q_{oss}	-	53	74	nC	V_{DD}=20 V, V_{GS}=0 V

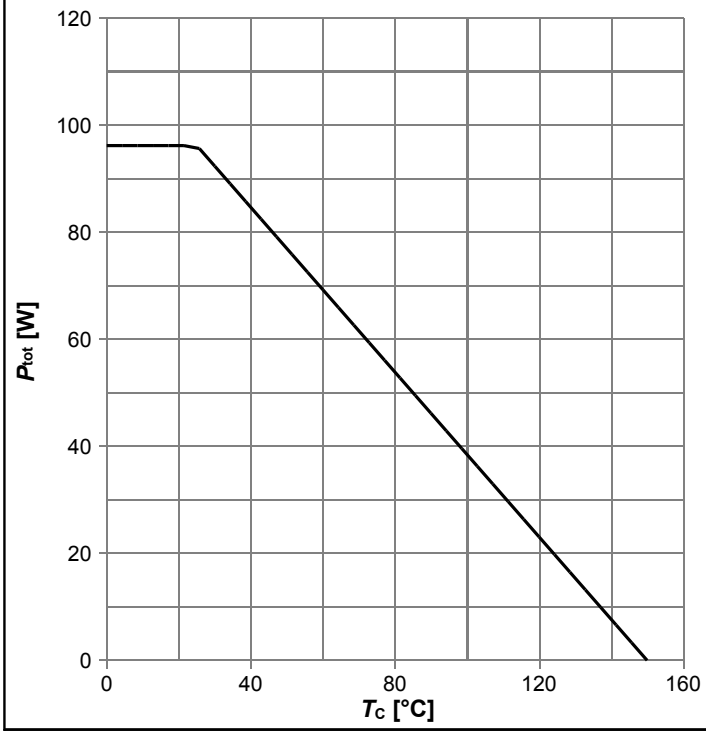
Table 7 Reverse diode

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode continuous forward current	I_S	-	-	96	A	T_C=25 °C
Diode pulse current	$I_{S,pulse}$	-	-	780	A	T_C=25 °C
Diode forward voltage	V_{SD}	-	0.56	0.7	V	V_{GS}=0 V, I_F=12 A, T_j=25 °C
Reverse recovery charge	Q_{rr}	-	20	-	nC	V_R=20 V, I_F=12 A, di_F/dt=400 A/µs

[1)] See ″Gate charge waveforms″ for parameter definition
[2)] Defined by design. Not subject to production test

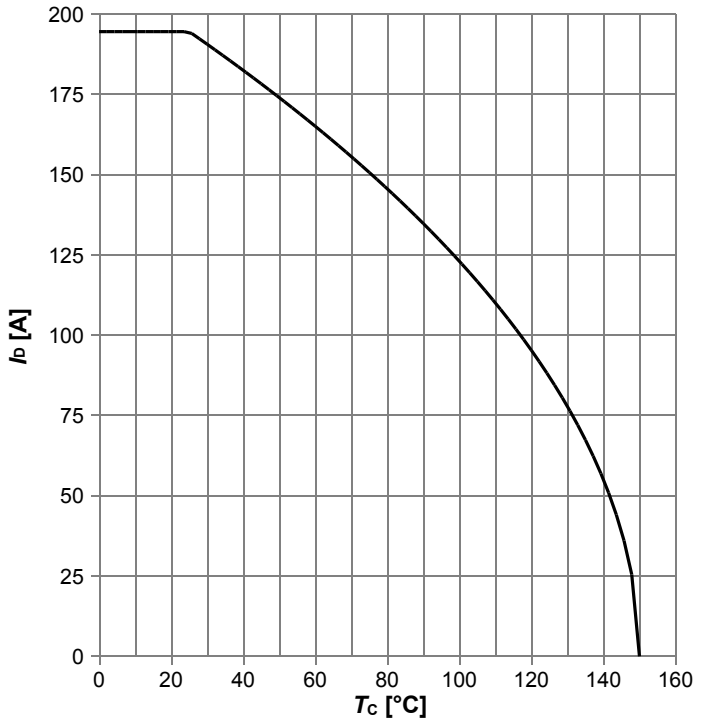
4 Electrical characteristics diagrams

Diagram 1: Power dissipation



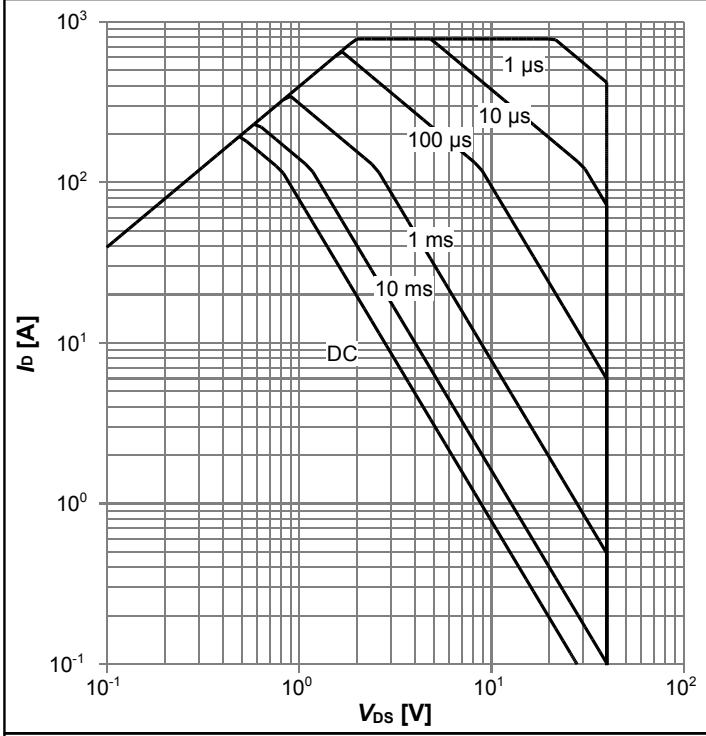
$P_{tot}=f(T_C)$

Diagram 2: Drain current



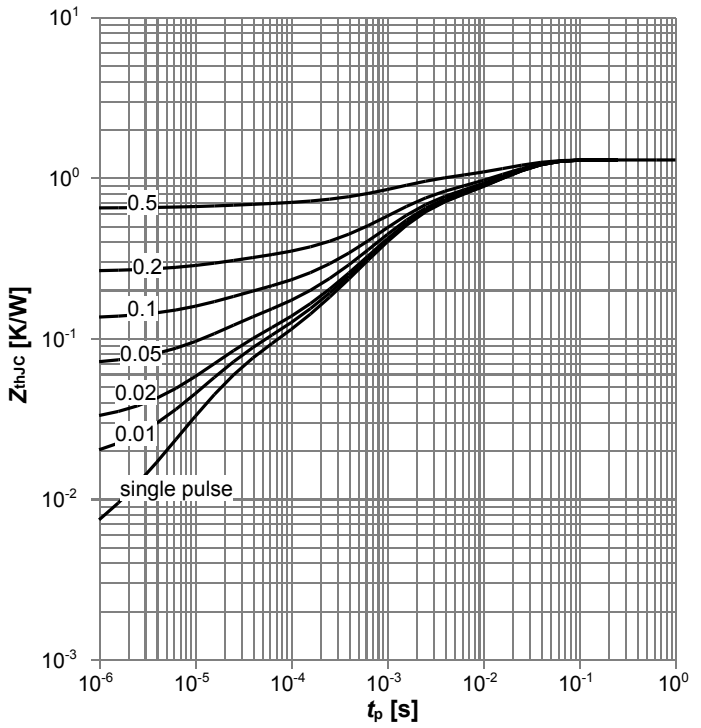
$I_D=f(T_C)$; $V_{GS}\geq 10$ V

Diagram 3: Safe operating area



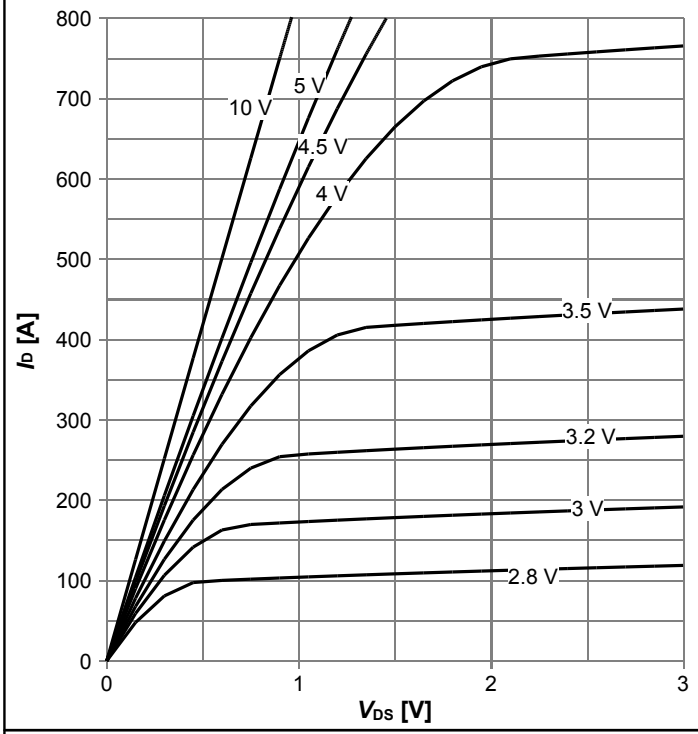
$I_D=f(V_{DS})$; $T_C=25$ °C; $D=0$; parameter: t_p

Diagram 4: Max. transient thermal impedance



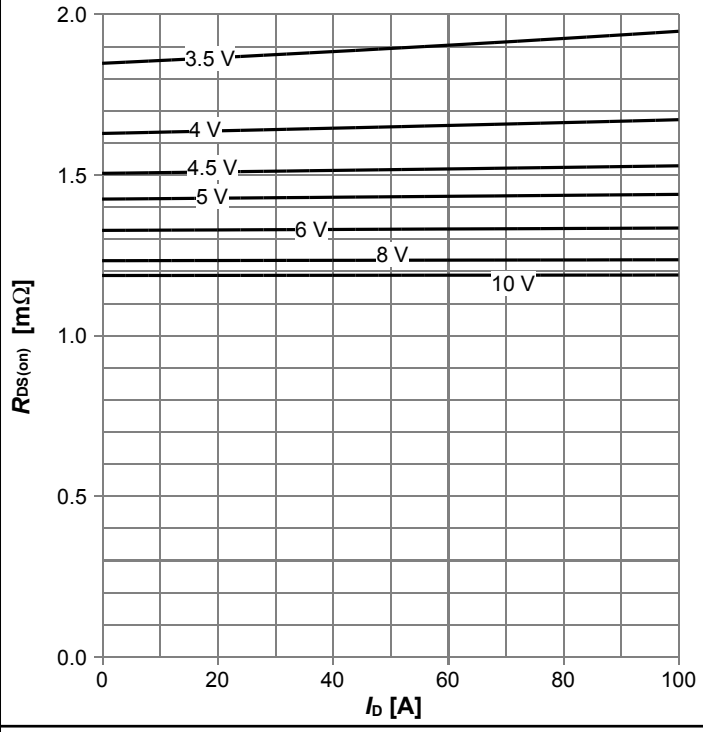
$Z_{thJC}=f(t_p)$; parameter: $D=t_p/T$

Diagram 5: Typ. output characteristics



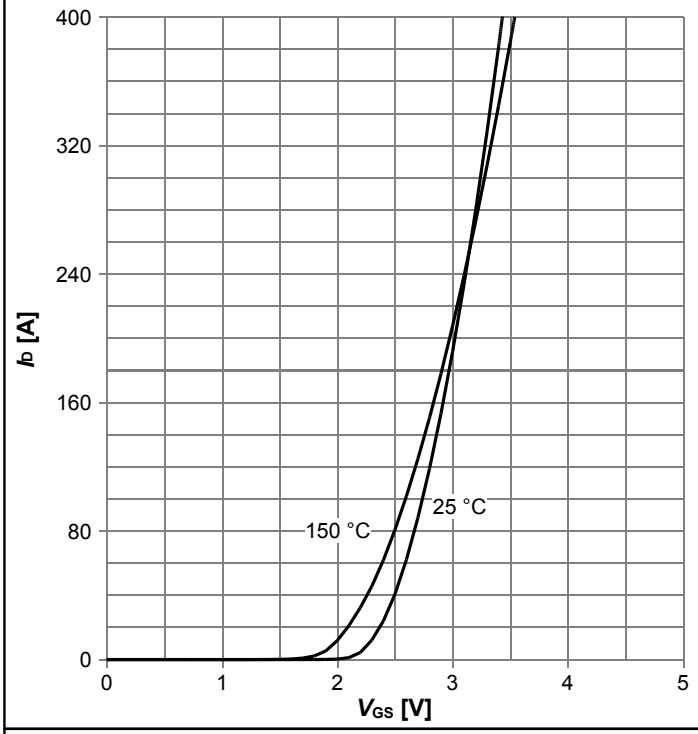
$I_D=f(V_{DS})$; $T_j=25$ °C; parameter: V_{GS}

Diagram 6: Typ. drain-source on resistance



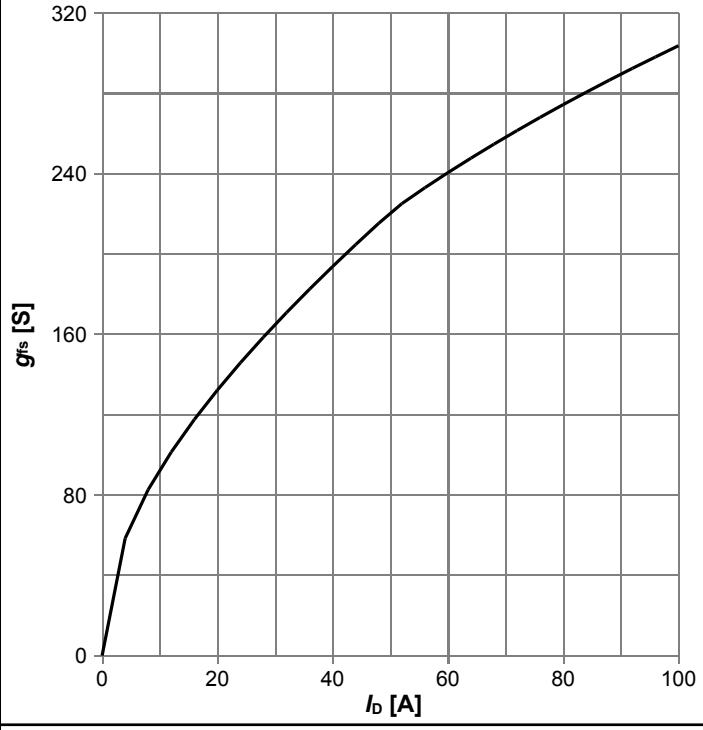
$R_{DS(on)}=f(I_D)$; $T_j=25$ °C; parameter: V_{GS}

Diagram 7: Typ. transfer characteristics



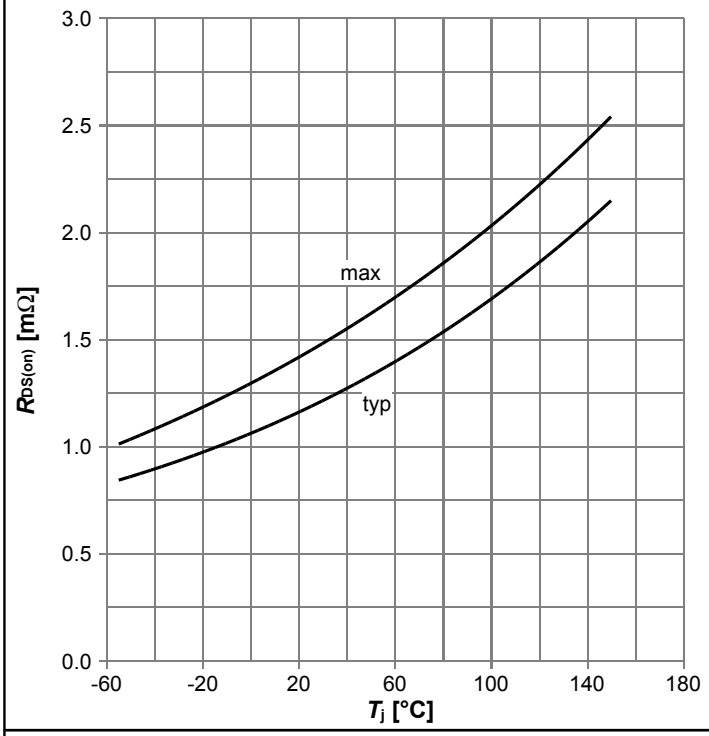
$I_D=f(V_{GS})$; $|V_{DS}|>2|I_D|R_{DS(on)max}$; parameter: T_j

Diagram 8: Typ. forward transconductance



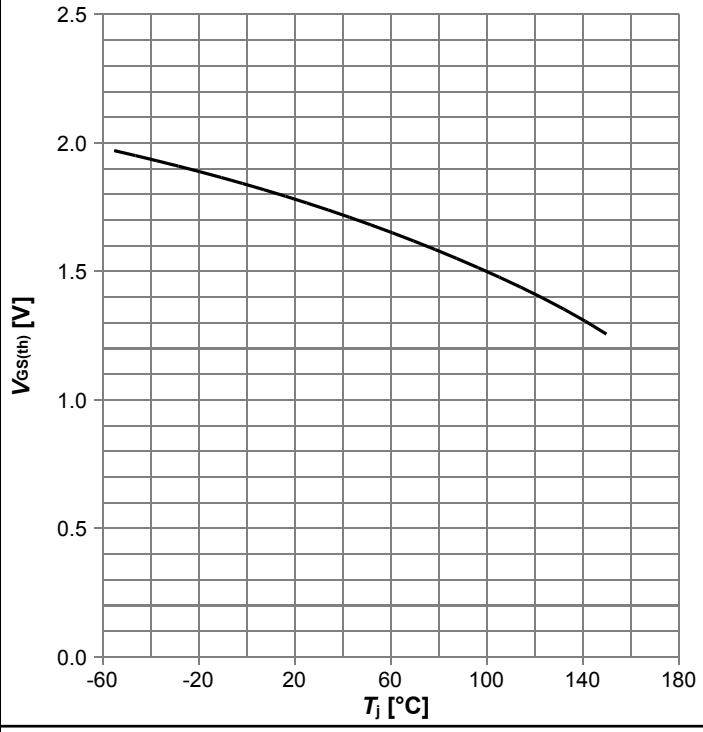
$g_{fs}=f(I_D)$; $T_j=25$ °C

Diagram 9: Drain-source on-state resistance



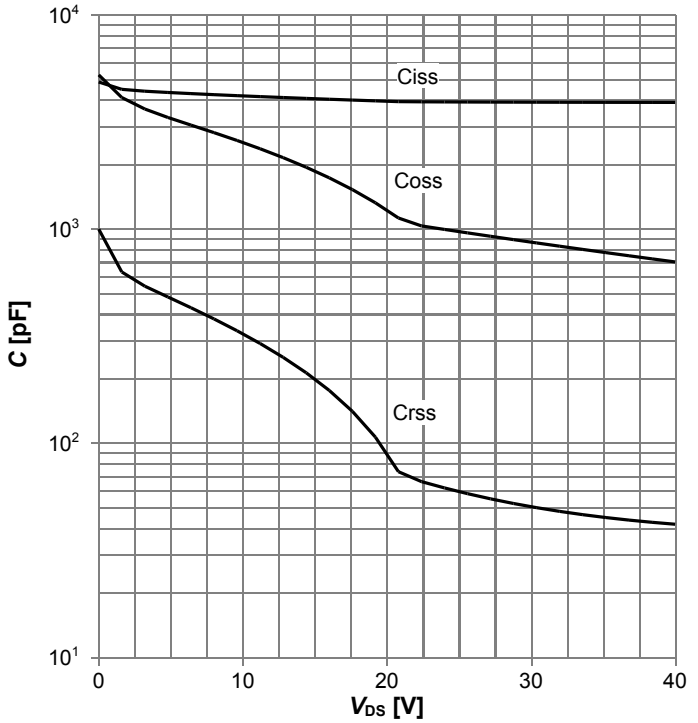
$R_{DS(on)}$=f(T_j); I_D=50 A; V_{GS}=10 V

Diagram 10: Typ. gate threshold voltage



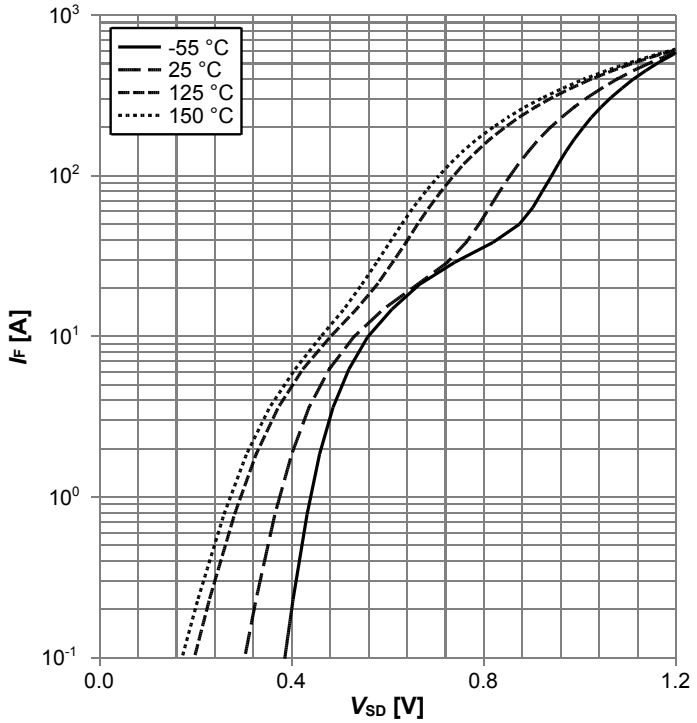
$V_{GS(th)}$=f(T_j); V_{GS}=V_{DS}; I_{DS}=10mA

Diagram 11: Typ. capacitances



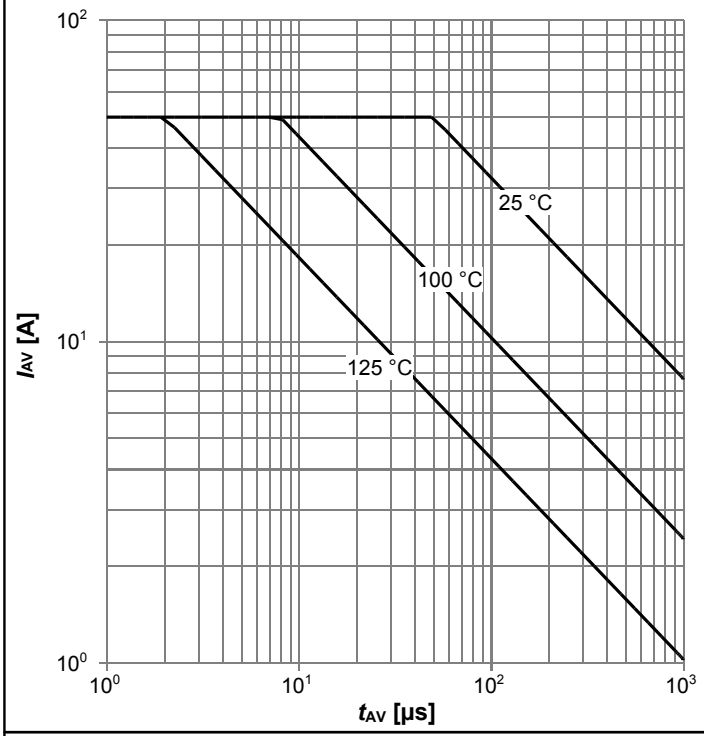
C=f(V_{DS}); V_{GS}=0 V; f=1 MHz

Diagram 12: Forward characteristics of reverse diode



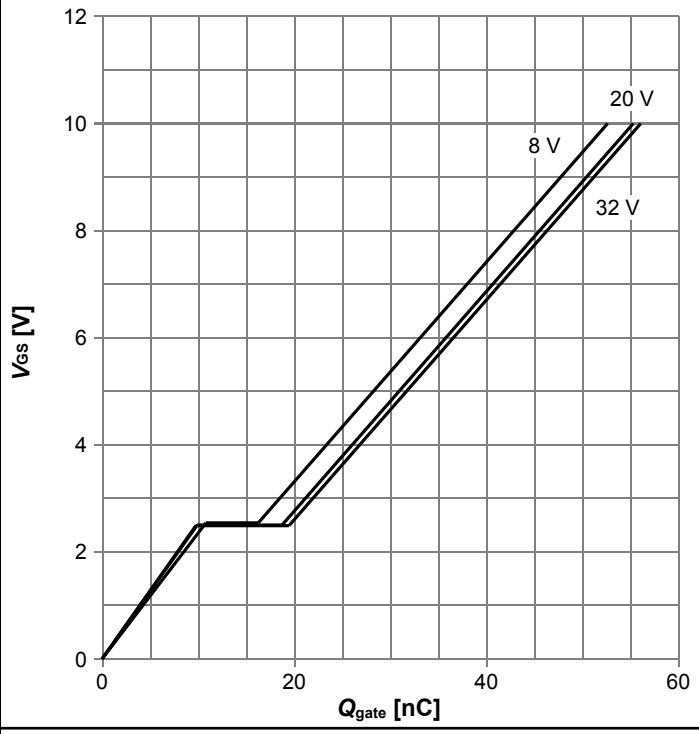
I_F=f(V_{SD}); parameter: T_j

Diagram 13: Avalanche characteristics



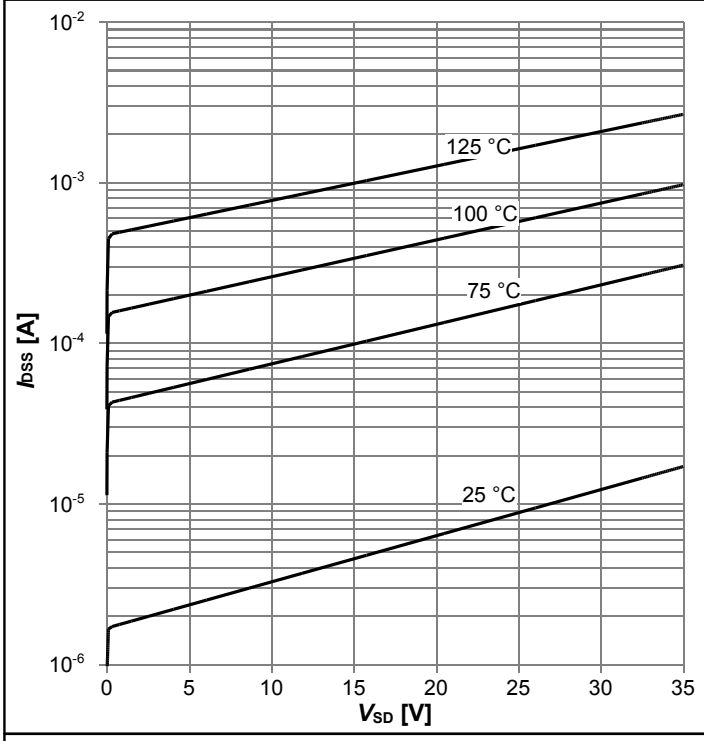
I_{AS}=f(t_{AV}); R_{GS}=25 Ω; parameter: $T_{j(start)}$

Diagram 14: Typ. gate charge



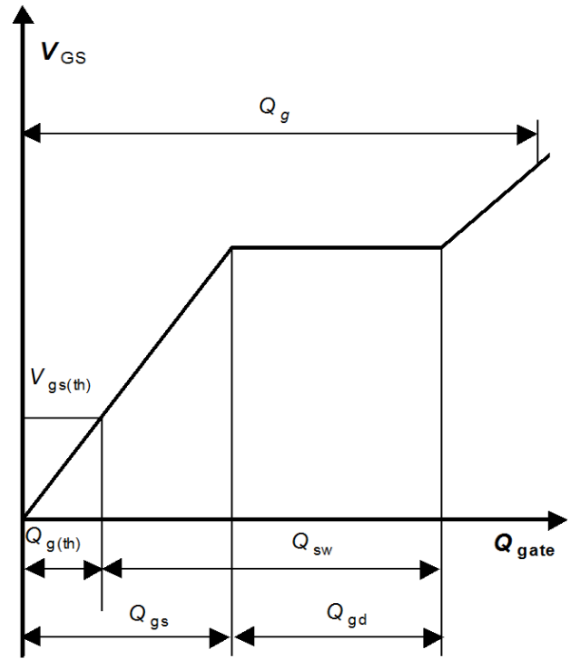
V_{GS}=f(Q_{gate}); I_D=50 A pulsed; parameter: V_{DD}

Diagram 15: Typ. drain-source leakage current

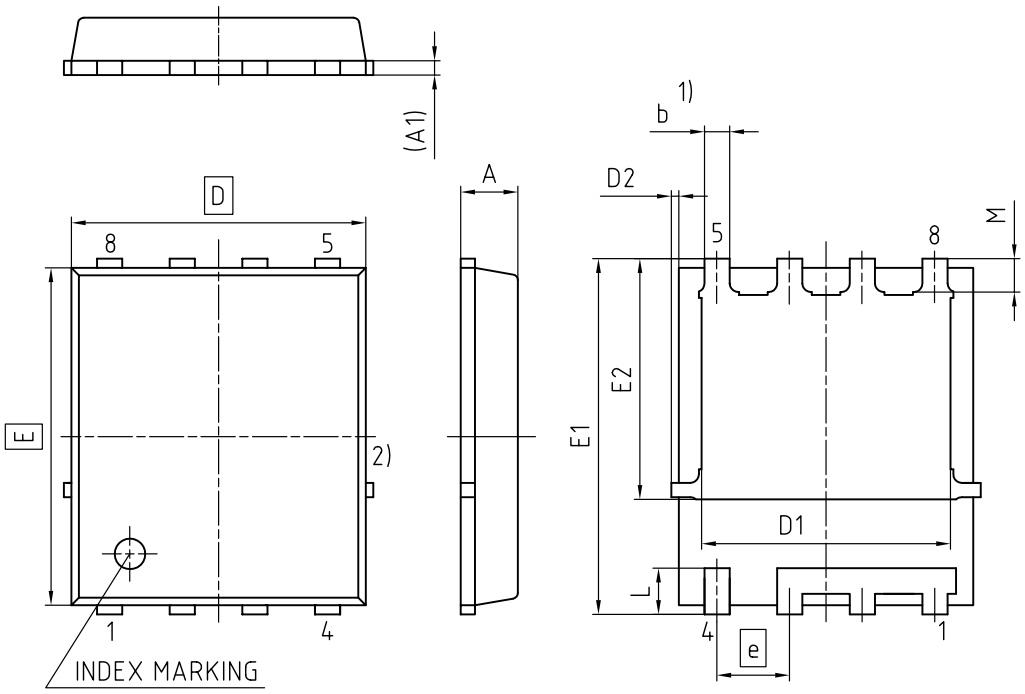


I_{DSS}=f(V_{DS}); V_{GS}=0 V; parameter: T_j

Diagram Gate charge waveforms



5 Package Outlines



1) EXCLUDING MOLD FLASH
2) REMOVAL ON MOLD GATE
INTRUSION 0.1 MM
PROTRUSION 0.1 MM
LEAD LENGTH UP TO ANTI FLASH LINE
ALL METAL SURFACES ARE PLATED, EXCEPT AREA OF CUT

DIMENSION	MILLIMETERS	
	MIN.	MAX.
A	0.90	1.20
A1	0.15	0.35
b	0.26	0.54
D	4.80	5.35
D1	3.70	4.40
D2	0.02	0.23
E	5.70	6.10
E1	5.90	6.42
E2	3.88	4.42
e	1.27	
L	0.69	0.90
M	0.45	0.69

DOCUMENT NO.	Z8B000193699
REVISION	03
SCALE 10:1	0 1 2 3mm
EUROPEAN PROJECTION	
ISSUE DATE	19.06.2019

Figure 1 Outline TDSON-8 FL, dimensions in mm

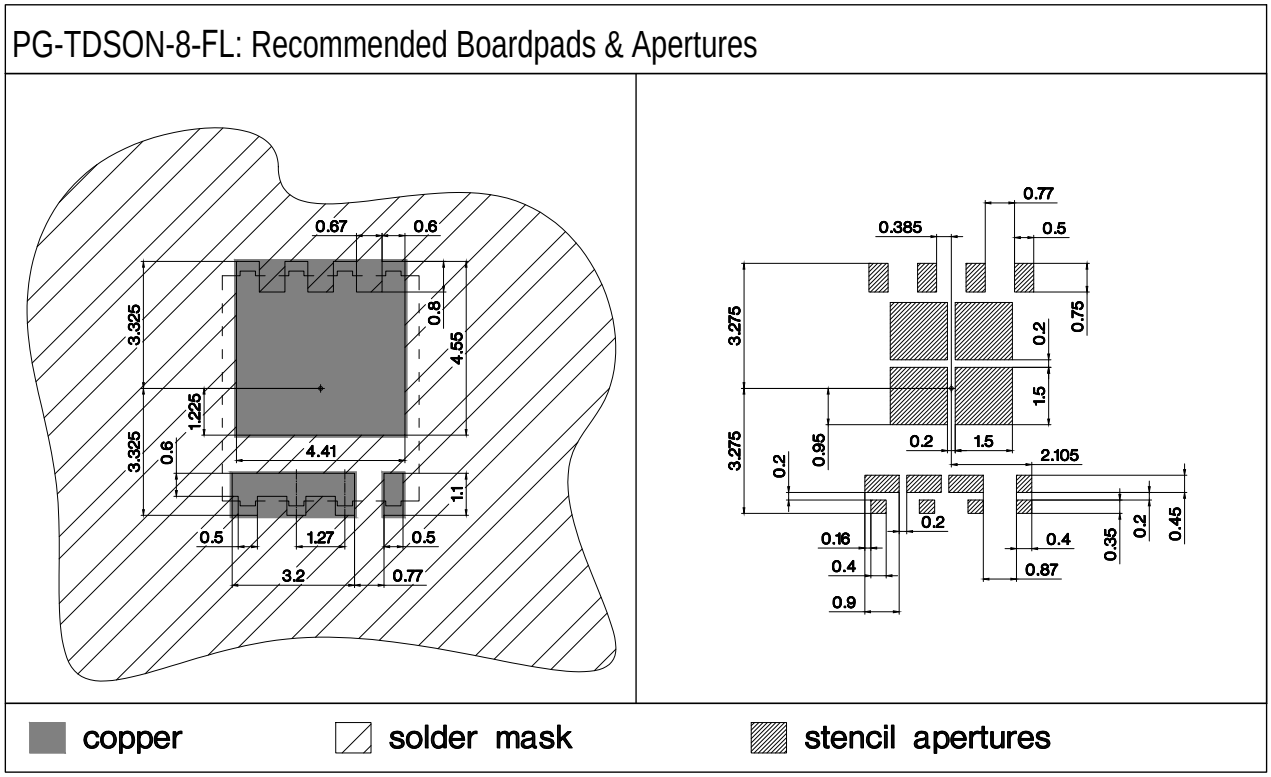


Figure 2 Outline Boardpads (TDSON-8 FL)

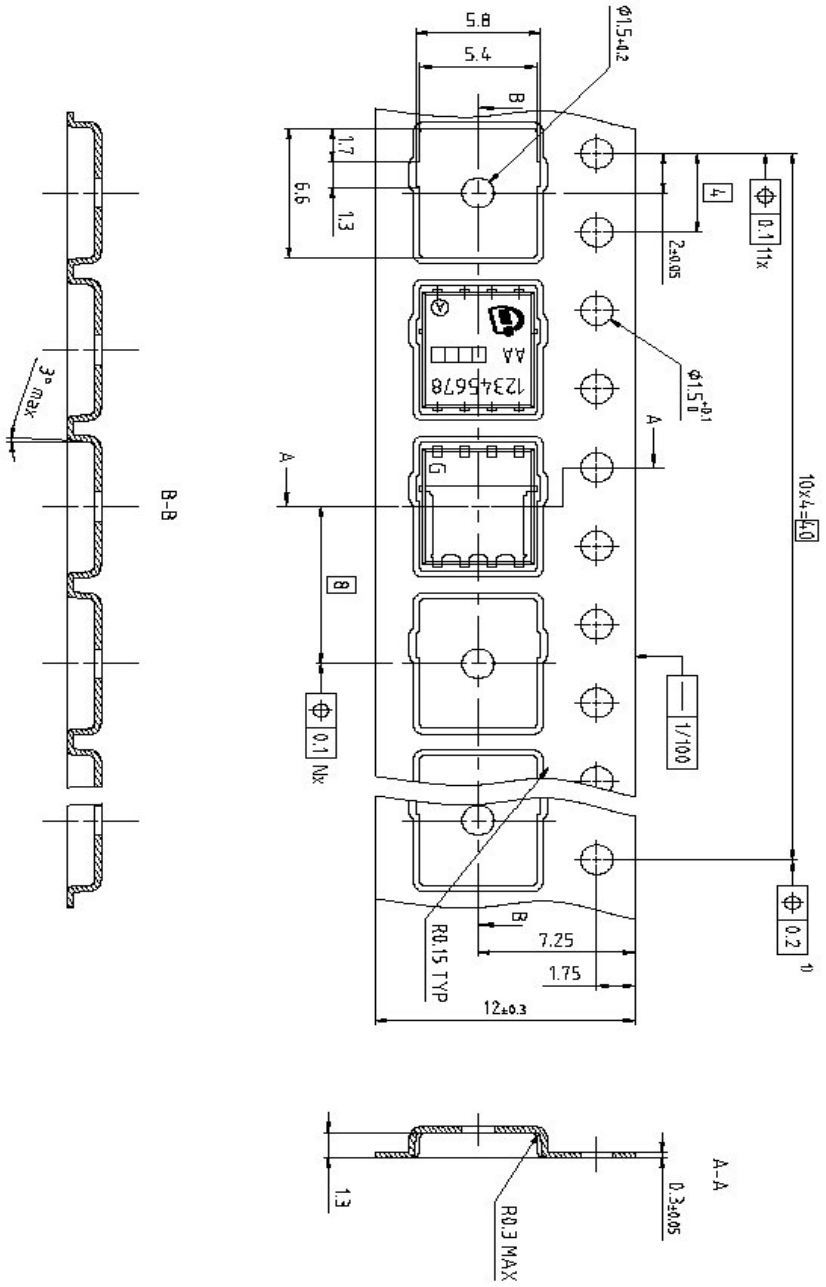


Figure 3 Outline Tape (TDSON-8 FL)

Revision History

BSC014N04LSI

Revision: 2020-05-15, Rev. 2.4

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.2	2016-05-04	Update footnotes and insert max values
2.3	2019-10-01	Update package drawings
2.4	2020-05-15	Update current rating

Trademarks
All referenced product or service names and trademarks are the property of their respective owners.

We Listen to Your Comments
Any information within this document that you feel is wrong, unclear or missing at all? Your feedback will help us to continuously improve the quality of this document. Please send your proposal (including a reference to this document) to:
erratum@infineon.com

Published by
Infineon Technologies AG
81726 München, Germany
© 2020 Infineon Technologies AG
All Rights Reserved.

Legal Disclaimer
The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics (“Beschaffenheitsgarantie”) .

With respect to any examples, hints or any typical values stated herein and/or any information regarding the application of the product, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights of any third party.
In addition, any information given in this document is subject to customer’s compliance with its obligations stated in this document and any applicable legal requirements, norms and standards concerning customer’s products and any use of the product of Infineon Technologies in customer’s applications.
The data contained in this document is exclusively intended for technically trained staff. It is the responsibility of customer’s technical departments to evaluate the suitability of the product for the intended application and the completeness of the product information given in this document with respect to such application.

Information
For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office (www.infineon.com).

Warnings
Due to technical requirements, components may contain dangerous substances. For information on the types in question, please contact the nearest Infineon Technologies Office.
The Infineon Technologies component described in this Data Sheet may be used in life-support devices or systems and/or automotive, aviation and aerospace applications or systems only with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support, automotive, aviation and aerospace device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

ENTEGRECİ

Bu belge www.entegreci.com üzerinden sunulmaktadır.

Elektronik komponent tedarikinde Entegreci

Entegreci, Eskişehir merkezli, Türkiye geneline satış yapan bir elektronik komponent mağazasıdır. Entegreler (IC), mikrodenetleyiciler, transistörler, diyotlar, pasif elemanlar, konnektörler, modüller ve geliştirme kartları tek adetten seri üretim adetlerine kadar satılır. Ürün sayfalarında güncel stok durumunu, fiyatı ve datasheet bağlantısını bulabilirsiniz.

Parça koduyla arama

Üretici parça numarasını yazın; stok ve fiyatı hemen görün.

www.entegreci.com

Ürün kategorileri

Entegreden kapasitöre tüm elektronik komponent kategorileri.

Kategorilere göz atın

Üreticiler

Aradığınız üreticinin ürünlerini tek sayfada inceleyin.

Üreticileri görün

Toplu alım ve teklif

Listede olmayan ya da yüksek adetli parçalar için teklif isteyin.

Teklif isteyin

www.entegreci.com | **destek@entegreci.com** | **0850 305 90 34**

Entegreci is an online electronic components store based in Türkiye. Search by manufacturer part number to see stock, prices and datasheets for integrated circuits, microcontrollers, transistors, passive components and connectors, or request a quote for parts that are not listed.

Bu sayfa Entegreci tarafından eklenmiştir. Belgenin önceki sayfaları asıl yayıncısına aittir ve içeriği değiştirilmemiştir; en güncel sürüm için belgenin yayıncısına başvurun.